

## EPC3127-X



- Used in SMPS Flyback Topology
- Designed for use with Power Integration Chip
- Reinforced Insulation (Triple Insulated Wire)
- UL 94V-0 Recognized Components
- UL 1446 Class F Insulation System
- Very Low Core Loss

### Electrical Parameters @ 25° C

PCA Part Number	Chipset	Voltage (Vdc)				Primary OCL ( $\mu\text{H} \pm 10\%$ ) @ 10 KHz, 0.1 Vrms	Current (Amp.)			Schematic
		V in	V out 1	V out 2	V out 3		Sec. 1	Sec. 2	Sec. 3	
EPC3127-1	TNY268P	120-375	5	N	15	1900	3.0	N	.05	A
	TNY266P	120-375	5	N	15	1900	2.0	N	.05	A
EPC3127-2	TOP232Y/TOP242Y	120-375	5	3.3	15	2400	2.0	2	.05	B
EPC3127-3	TOP244P	120-375	13.55	N	15	475	1.2	N	.05	A
EPC3127-4	TNY267	120-375	3.3	N	15	2800	2.0	N	.05	A

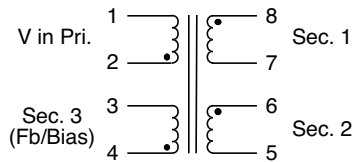
• Switching Frequency : 132 KHz • Isolation : 4500 Vrms •

### Dielectric Rating (Vrms)

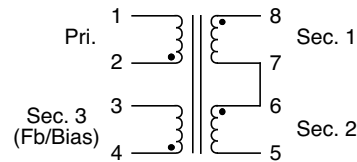
1 sec. 4500 or 60 sec. 3750	1 sec. 4500 or 60 sec. 3750	1 sec. 1500
Pri. to all Sec. Wdg's & Core	Between Sec. Wdg's to Core	Between Pri. Wdg & Bias

• Note : "N" means Not Required/No Connections •

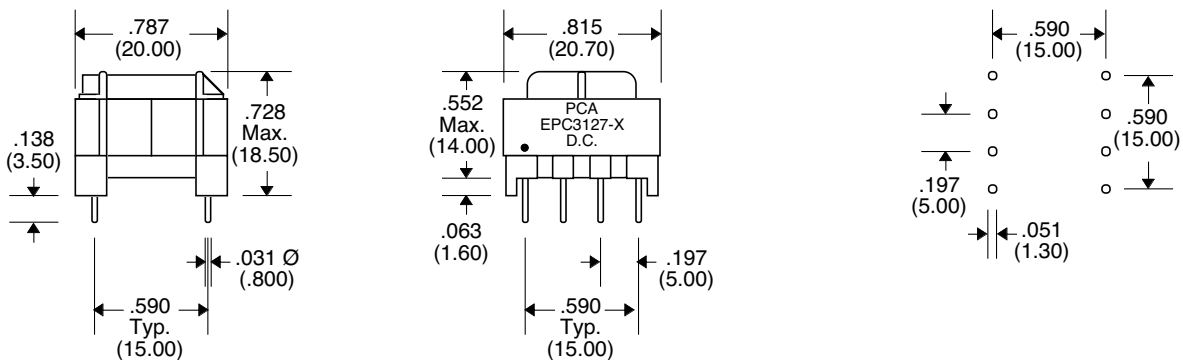
### Schematic A



### Schematic B



### Package



Unless Otherwise Specified Dimensions are in Inches /mm  $\pm .010 / .25$